

**Amendments to the Specification:**

**On page 6, please replace paragraph [0012] with the following paragraph:**

[0012] The laminate 106 can be applied to the die 100 using known optically transparent adhesives 105. In certain embodiments, this adhesive can cover a large portion of the die 100, including the photonic device 104, thus firmly securing the laminate 106 to the die 100. Alternatively, the laminate 106 can include recessed cavities 118 which are not adhesively bonded to the die 100. Such cavities allow for the laminate 106 to be bonded to the die 100 while avoiding any risk of the adhesive interfering with the photonic device 104.